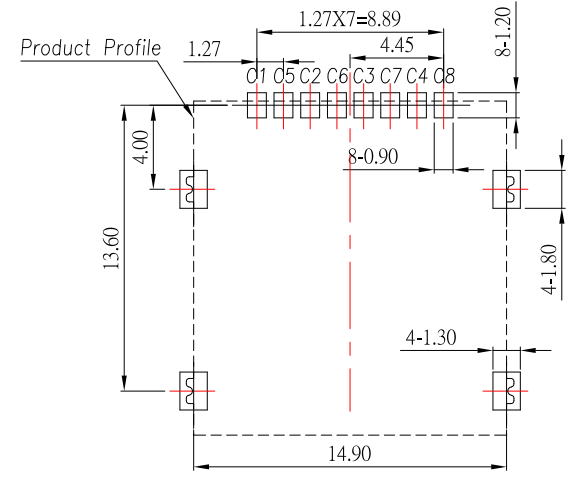
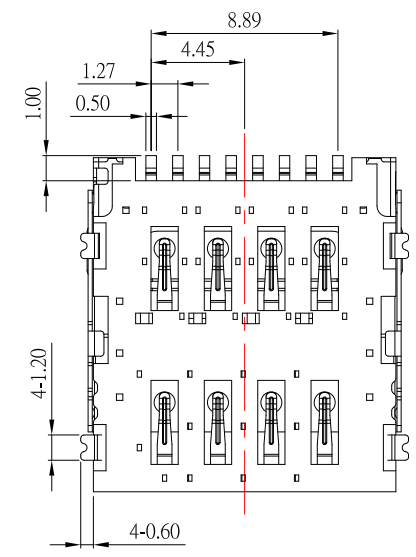
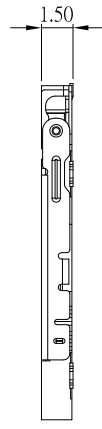
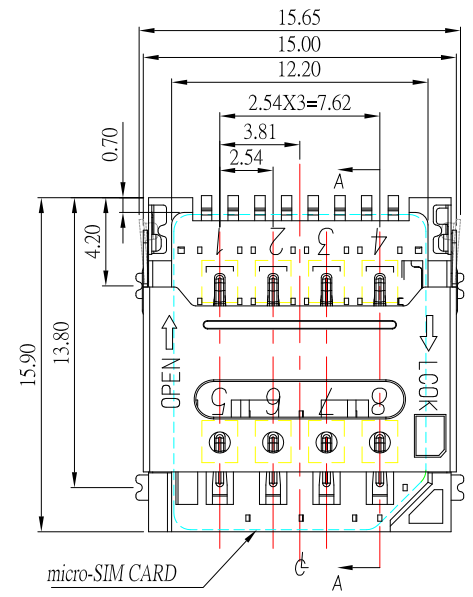
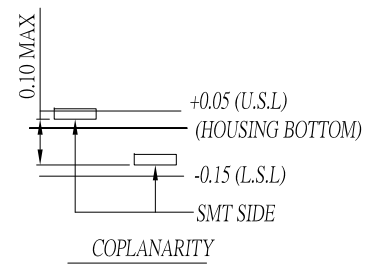
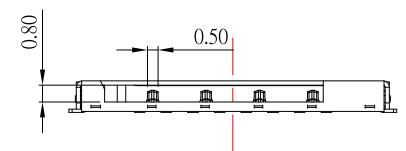


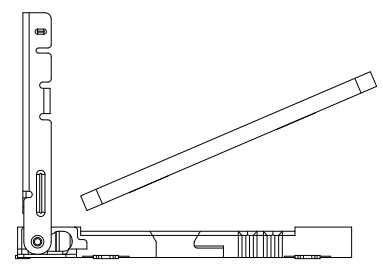
SECTION: A-A



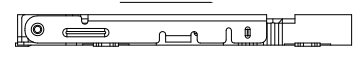
PCB LAYOUT



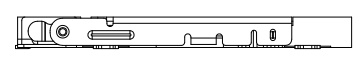
SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED



STEP 1 INSERT Micro-SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH

SPECIFICATION

- Electrical :
- Contact Resistance: 60 mΩ Max.
 - Insulation Resistance: 1,000 MΩ Min.
 - Dielectric Withstanding Voltage: 500 V AC

Material:

- Housing: Thermoplastic
- Contact: Phosphor Bronze
- Shell: SUS

Finish:

- Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- Shell: Nickel under Plated surface laye

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/22/18			
CHECKED BY:	DATE	FINISH	MODLE	MICRO SIM 8PIN H1.5 掀蓋
Jacky Chen	03/22/18			
APPROVED BY:	DATE	SCALE	DWG NO.	MSIM-08H150-S267
Tony Kao	03/22/18	1 : 1	PART NO.	MSIM-08H150-S267
		SHEET NO.	1 of 1	
				SIZE A4
				VER A0

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新尺寸及更新為A0版	Jack	032218